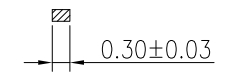
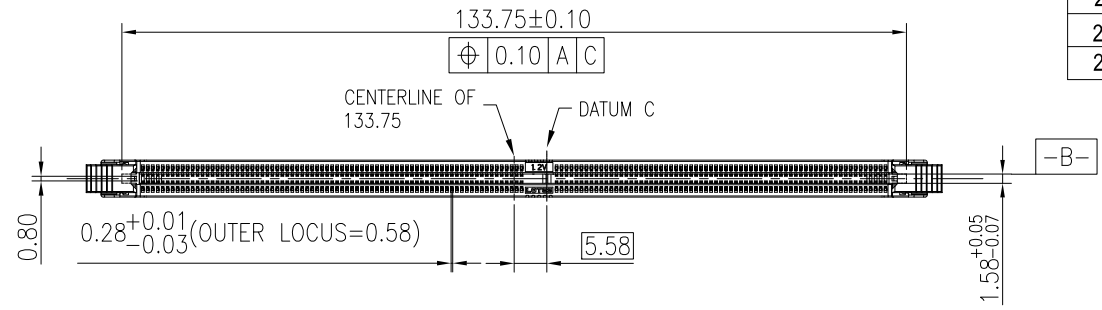
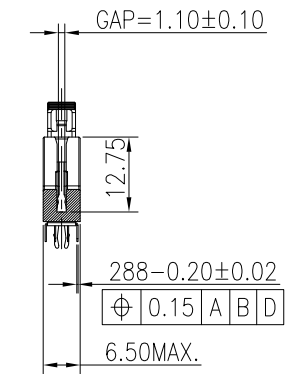
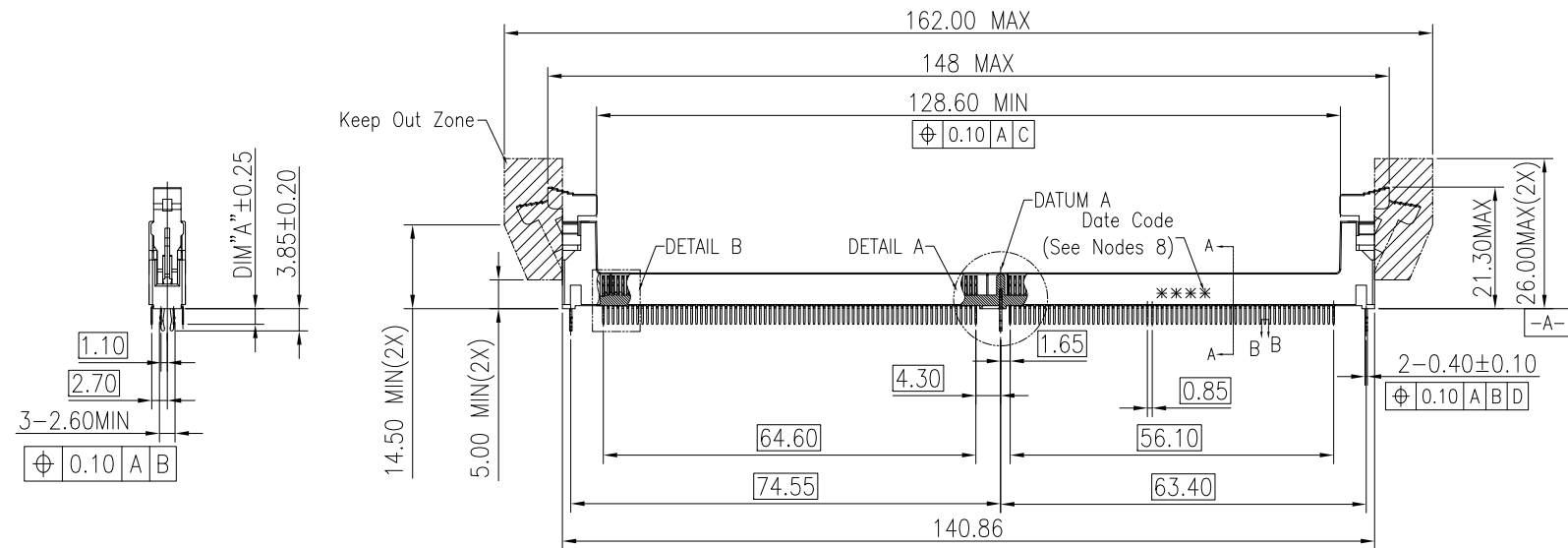


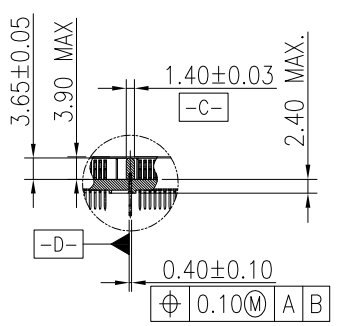
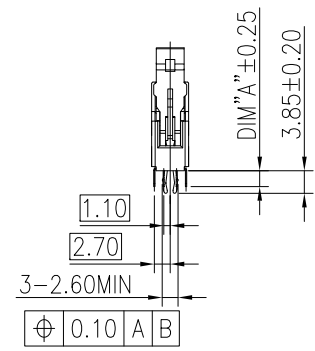
REV.	ECN NO./DESCRIPTION	DATE
2F	R140455	05/18'16
2G	R140455	04/24'17
2H	R140455	04/17'18



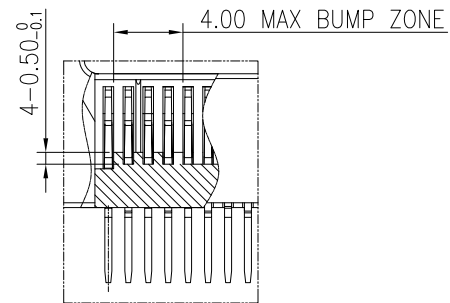
SOLDER TAIL SECTION
SECTION B-B(10:1)



SECTION A-A



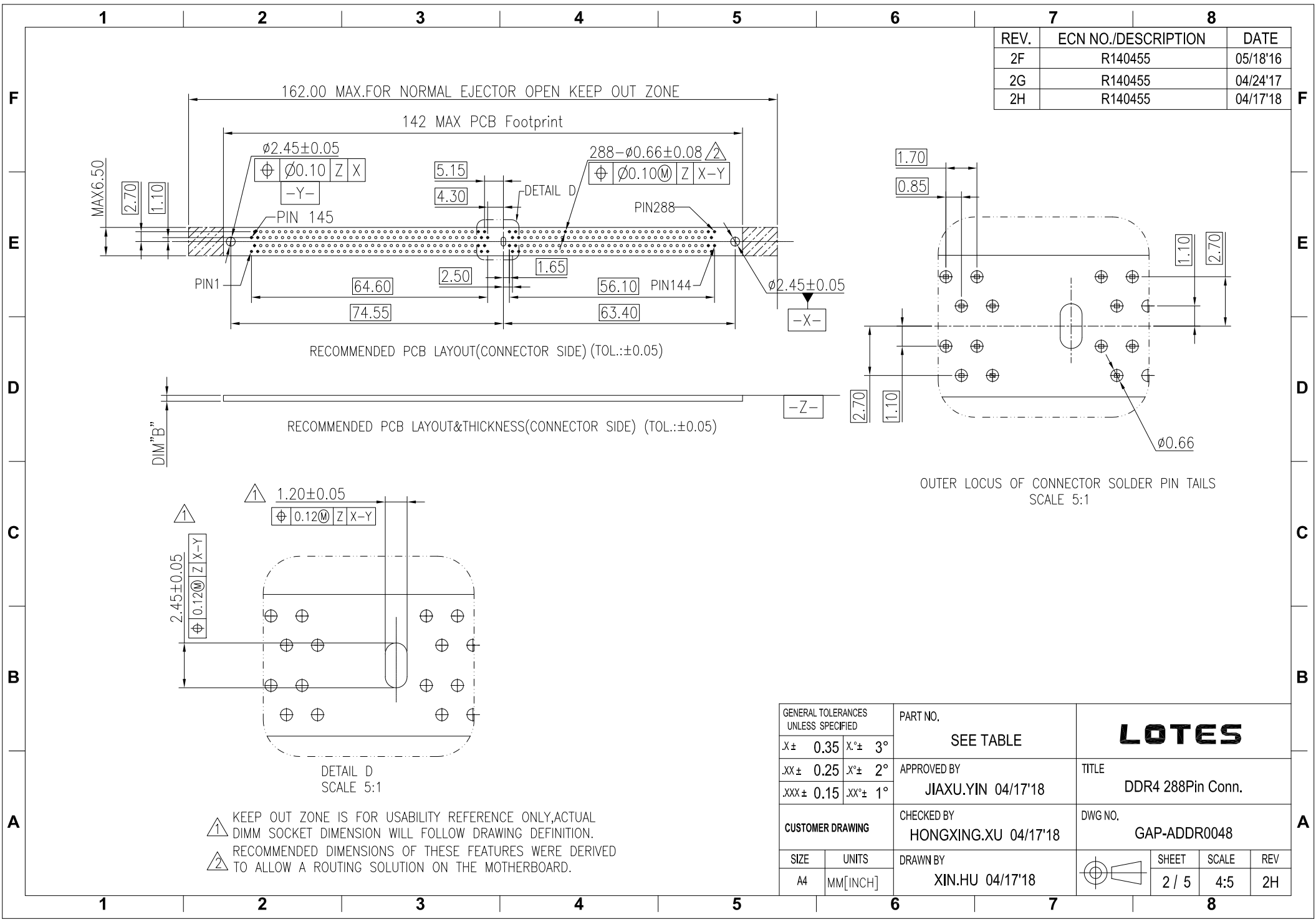
DETAIL A
SCALE 1:1



DETAIL A SCALE 4:1
BUMPER BLOCK-4PCS ON EACH SIDE
(8PCS TOTAL)

GENERAL TOLERANCES UNLESS SPECIFIED		PART NO. SEE TABLE	LOTES			
X± 0.35	X°± 3°					TITLE DDR4 288Pin Conn.
.XX± 0.25	.X°± 2°		APPROVED BY JIA XU.YIN 04/17'18	DWG NO. GAP-ADDR0048		
XXX± 0.15	.XX°± 1°	CHECKED BY HONGXING.XU 04/17'18	DRAWN BY XIN.HU 04/17'18			
CUSTOMER DRAWING						
SIZE A4	UNITS MM[INCH]			SHEET 1 / 5	SCALE 4:5	REV 2H

REV.	ECN NO./DESCRIPTION	DATE
2F	R140455	05/18'16
2G	R140455	04/24'17
2H	R140455	04/17'18



RECOMMENDED PCB LAYOUT(CONNECTOR SIDE) (TOL.:±0.05)

RECOMMENDED PCB LAYOUT&THICKNESS(CONNECTOR SIDE) (TOL.:±0.05)

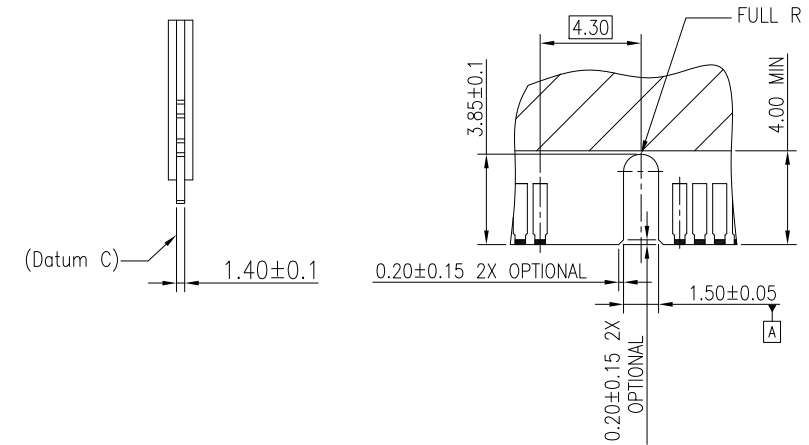
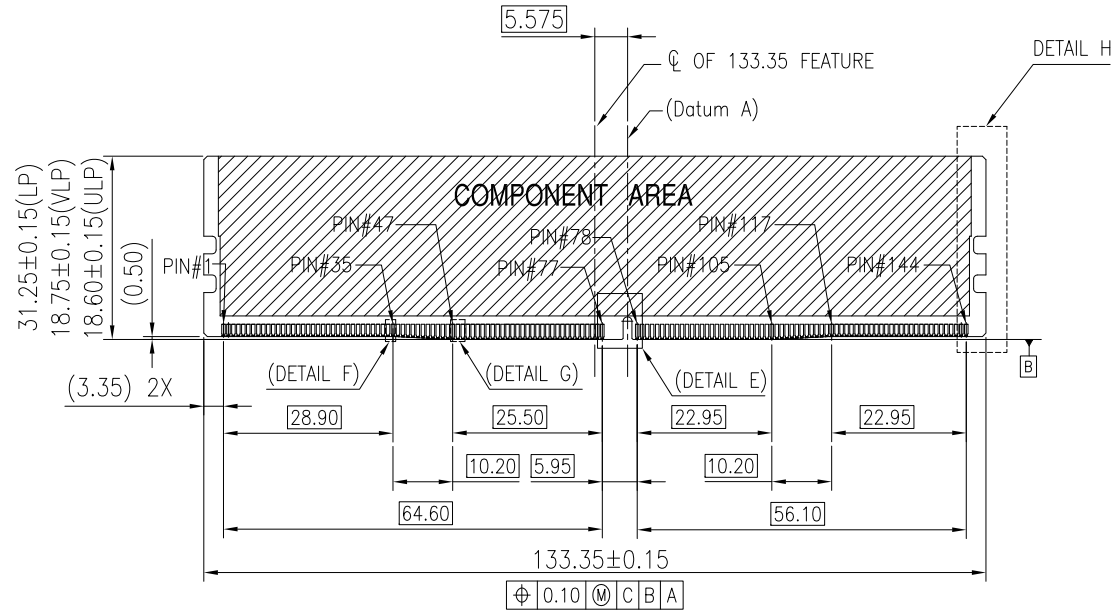
OUTER LOCUS OF CONNECTOR SOLDER PIN TAILS
SCALE 5:1

DETAIL D
SCALE 5:1

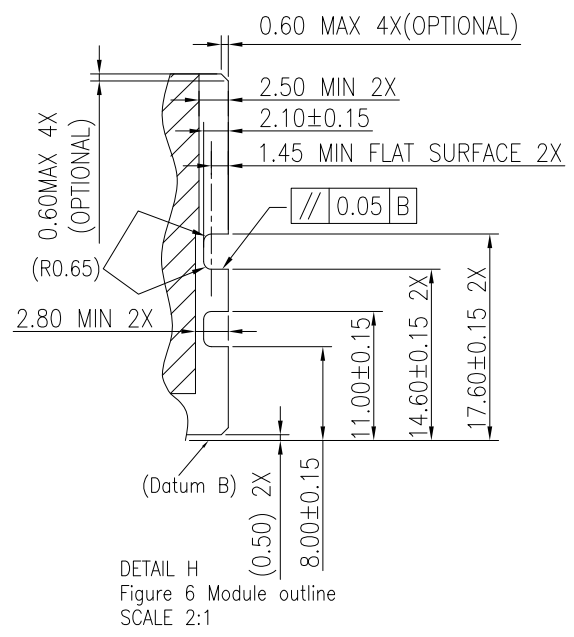
- ⚠ KEEP OUT ZONE IS FOR USABILITY REFERENCE ONLY,ACTUAL DIMM SOCKET DIMENSION WILL FOLLOW DRAWING DEFINITION.
- ⚠ RECOMMENDED DIMENSIONS OF THESE FEATURES WERE DERIVED TO ALLOW A ROUTING SOLUTION ON THE MOTHERBOARD.

GENERAL TOLERANCES UNLESS SPECIFIED		PART NO. SEE TABLE	LOTES			
X± 0.35	X°± 3°					APPROVED BY JIAXU.YIN 04/17'18
.XX± 0.25	.X°± 2°					
.XXX± 0.15	.XX°± 1°					
CUSTOMER DRAWING		CHECKED BY HONGXING.XU 04/17'18	DWG NO. GAP-ADDR0048			
SIZE A4	UNITS MM[INCH]	DRAWN BY XIN.HU 04/17'18		SHEET 2 / 5	SCALE 4:5	REV 2H

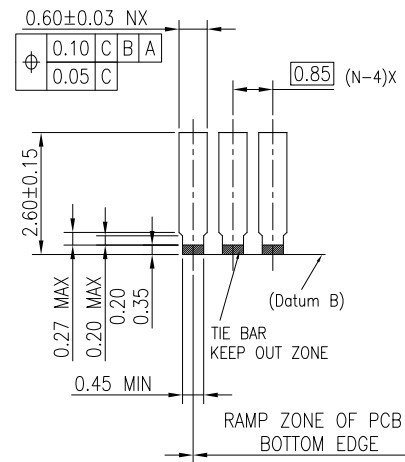
REV.	ECN NO./DESCRIPTION	DATE
2F	R140455	05/18'16
2G	R140455	04/24'17
2H	R140455	04/17'18



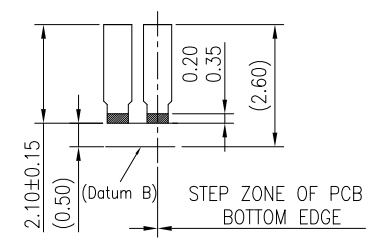
DETAIL E
SCALE 4:1



DETAIL H
Figure 6 Module outline
SCALE 2:1



DETAIL G
SCALE 8:1



DETAIL F
SCALE 8:1

GENERAL TOLERANCES UNLESS SPECIFIED		PART NO. SEE TABLE	LOTES		
X± 0.35	X°± 3°				
.XX± 0.25	.X°± 2°				
XXX± 0.15	.XX°± 1°	CHECKED BY HONGXING.XU 04/17'18	DWG NO. GAP-ADDR0048		
CUSTOMER DRAWING					
SIZE A4	UNITS MM[INCH]	DRAWN BY XIN.HU 04/17'18	SHEET 3 / 5	SCALE 4:5	REV 2H

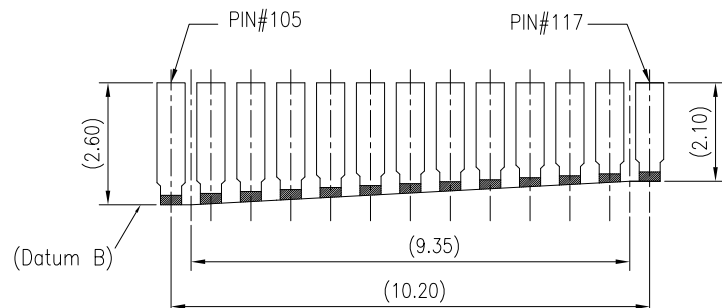
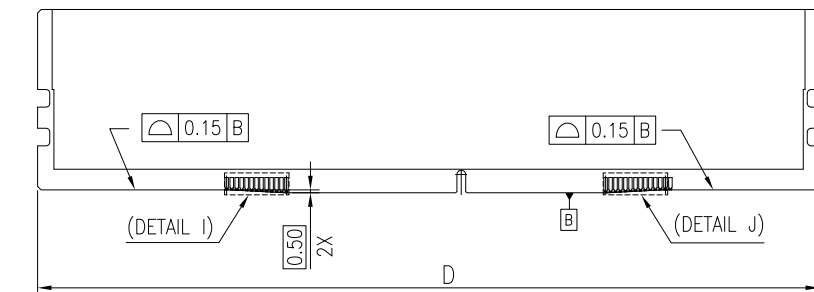
REV.	ECN NO./DESCRIPTION	DATE
2F	R140455	05/18'16
2G	R140455	04/24'17
2H	R140455	04/17'18

NOTES:

- MATERIAL: HOUSING: HIGH TEMPERATURE THERMOPLASTIC , UL94V-0, COLOR:SEE TABLE.
EJECTOR: THERMOPLASTIC, UL94V-0, COLOR: SEE TABLE.
CONTACT: SPECIFIC COPPER OR PHOSPHOR BRONZE.
HOOK: SUS301.
- FINISH: CONTACT: 50u"OR 90u"MIN NICKEL UNDERPLATED;
100u"MIN MATTE TIN PLATED ON SOLDER AREA.
GOLD PLATING AT CONTACT AREA,THICKNESS SEE TABLE
HOOK: NO PLATING.
- RECOMMENDED MODULE LAYOUT SHOULD BE MO-XXX FROM JEDEC.
- WAVE SOLDERING TEMPRATURE:
THE LATCH SHALL BE CLOSED;
THE CONNECTOR SHALL BE MOUNTED ON THE PCB;
OF THE SOLDER SHALL BE 260±5°C AND IMMERSION DURATION:10±1 SECONDS.
- MECHANICAL PERFORMANCE:
5-1. INSERTION FORCE-MODULE TO CONNECTOR: 106.8N MAX
5-2. INSERTION FORCE-CONNECTOR TO BOARD: 75N MAX
5-3. DURABILITY: 25 CYCLES
5-4. RETENTION FORCE: 300gf/PIN MIN
5-5. UNMATING FORCE(PER PIN PAIR): 14gf MIN
- ELECTRICAL PERFORMANCE:
6-1. VOLTAGE RATING: 1.2V±0.1V
6-2. CURRENT RATING: 0.75A PER PIN MAX
6-3. IMPEDANCE: 50ohm
6-4. LLCR: 10mΩ MAX.(INITIAL), ΔR: 10mΩ MAX
6-5. INSULATION RESISTANCE: 500V DC, 1MΩ MIN
6-6. DIELECTRIC WITHSTANDING VOLTAGE: APPLY 500V AC, NO BREAKDOWN.
- ROHS AND HF COMPLIANT.
- D/C ** ** WEEK
YEAR
- PRODUCT NUMBER NOTE:

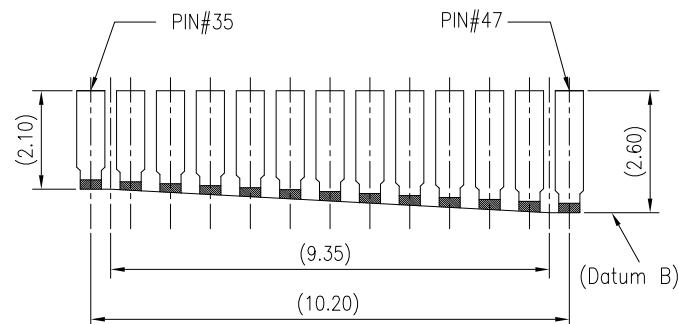
ADDRXXXX-XXXXC

- TRAY PACKING
- PRODUCT SERIES NUMBER
- P:HF COMPLIANT/K:ROHS COMPLIANT
- TYPE SERIES NUMBER
- DDR TYPE
- FINISHED PRODUCT



DETAIL J

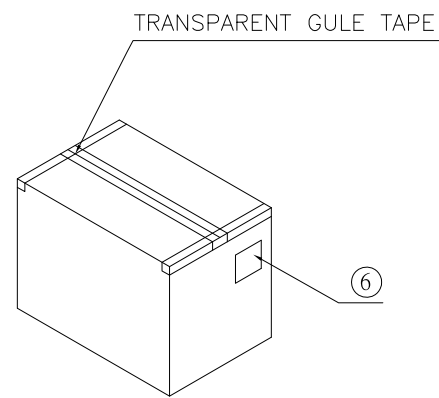
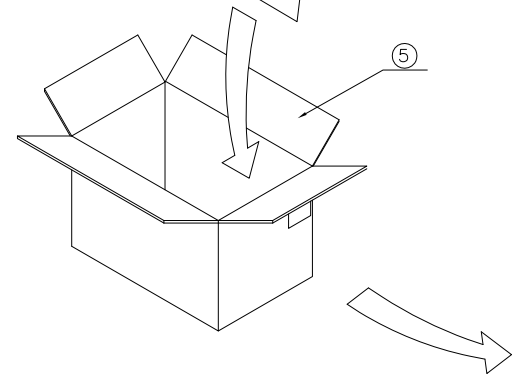
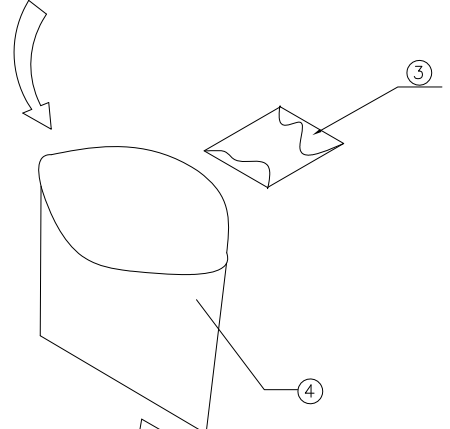
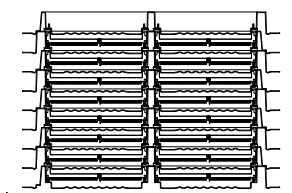
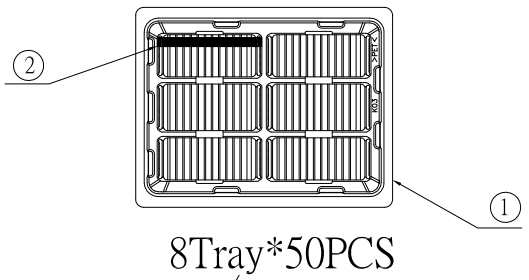
Figure 7 Step and ramp dimensions



DETAIL I

GENERAL TOLERANCES UNLESS SPECIFIED		PART NO.	LOTES			
X± 0.35	X°± 3°	SEE TABLE	TITLE DDR4 288Pin Conn.			
.XX± 0.25	.X°± 2°	APPROVED BY JIAXU.YIN 04/17'18				
.XXX± 0.15	.XX°± 1°	CHECKED BY HONGXING.XU 04/17'18	DWG NO. GAP-ADDR0048			
CUSTOMER DRAWING		DRAWN BY XIN.HU 04/17'18		SHEET	SCALE	REV
SIZE A4	UNITS MM[INCH]			4 / 5	4:5	2H

REV.	ECN NO.	DATE
2F	R140455	05/08'16
2G	R140455	04/24'17
2H	R140455	04/17'18



DDR Slot PACKING MATERIAL

NO.	NAME	P/N	SPEC (mm)	Q'TY
1	Tray	G09-A-35116-K03	360*280*30.5	9 PCS
2	DDR Slot	SEE DRAWING	SEE DRAWING	400PCS
3	DESICCANT	G09-7-00002-K03	50g/BAG	1 BAG
4	PE BAG	G09-6-50002-P03	520*320*460	1 PCS
5	CARTON	G09-1-35080-K01	367*285*250	1 PCS
6	LABEL	N/A		1 PCS

NOTES:
 1.ONE TRAY PACKING CAPACITY: 50PCS;
 2.CARTON PACKING CAPACITY: 400PCS.

GENERAL TOLERANCES UNLESS SPECIFIED		PART NO.	LOTES		
.X±0.35	X°±3'	SEE TABLE	TITLE DDR Slot PACKING		
.XX±0.25	.X°±2'	APPROVED BY JiaXu.Yin	DWG NO. GAP-ADDR0141		
.XXX±0.15	XX°±1.0'	CHECKED BY HongXing.Xu	DRAWN BY Xin.Hu		
SIZE A4	UNITS MM[INCH]			SHEET 5 / 5	SCALE 1:3
				REV 2H	

1

2

3

4

5

6

7

8

F

F

E

E

D

D

C

C

B

B

A

A

ADDR0047-K012C	HOUSING_BLACK,COTACT_15u"Au,HOOK;BALCK EJECTOR.	ROHS COMPLIANT	2.4mm	1.60~1.80mm
P.N	SPECIFICATION	REMARK	DIM"A"	DIM"B"

1

2

3

4

5

6

7

8